

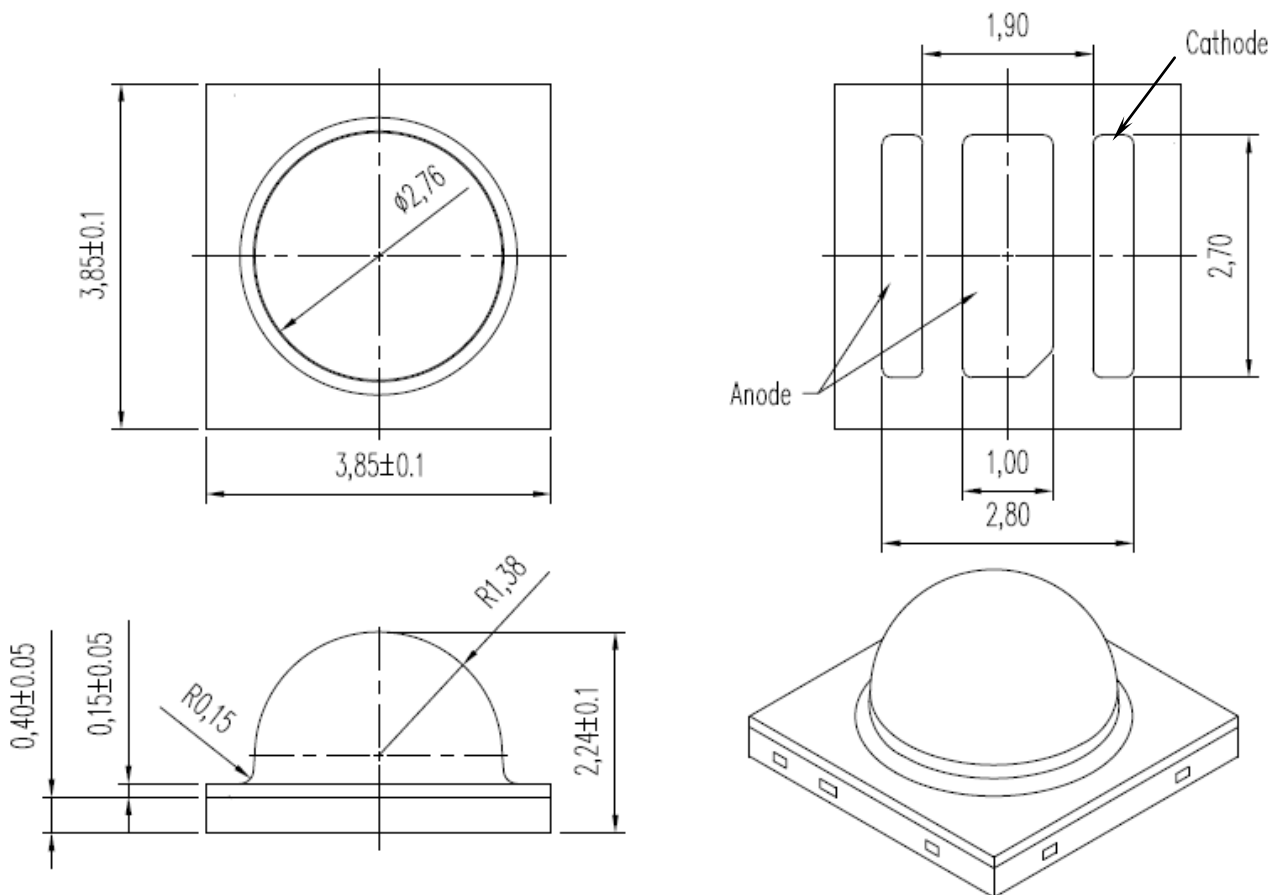
Features

- * High power LED light source
- * High performance, long life
- * High LED driving current
- * Meet ROHS, Green Product



REV.II AUG 2013

Package Dimensions



Notes:

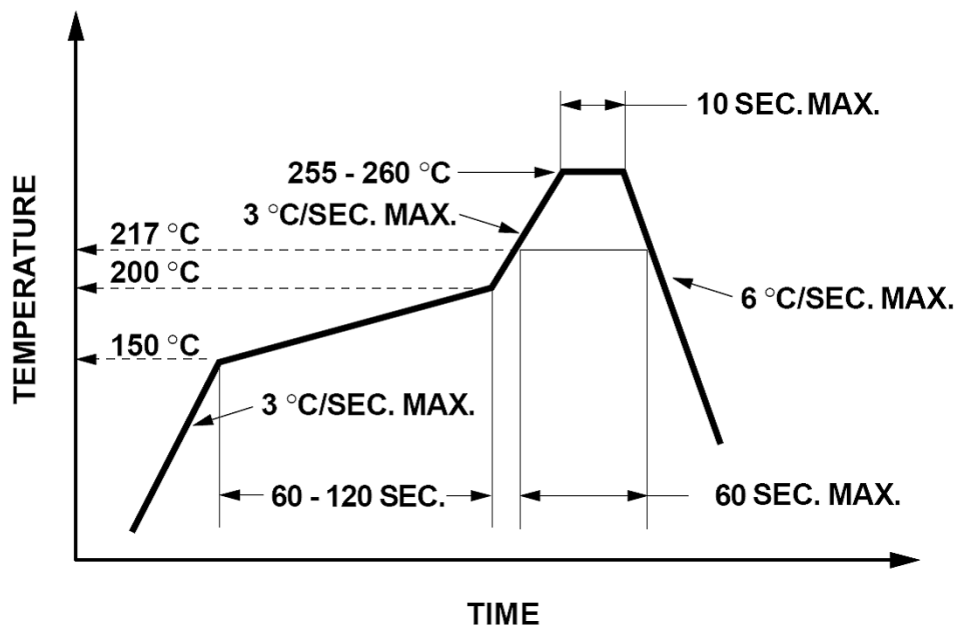
1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.10 mm (.004") unless otherwise noted.
3. Specifications are subject to change without notice.

ABSOLUTE MAXIMUM RATINGS AT TA=25°C

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation	1.8	W
Peak Forward Current (300pps, 10µs pulse)	5	A
Continuous Forward Current	1	A
Reverse Voltage	5	V
Operating Temperature Range	-40°C to + 100°C	
Storage Temperature Range	-55°C to + 100°C	
Junction Temperature	+140°C	
Infrared Soldering Condition	260°C For 10 Seconds	

Suggestion Profile:

Suggestion IR Reflow Profile For Pb Free Process





LITE-ON TECHNOLOGY CORPORATION.

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ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25°C

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Radiant Intensity	I_E	160	300	-	mW/sr	$I_F = 1 \text{ A}$
Total Radiant Flux	Φ_e	-	590	-	mW	$I_F = 1 \text{ A}$
Peak Emission Wavelength	λ_{Peak}	-	850	-	nm	$I_F = 1 \text{ A}$
Spectral Line Half-Width	$\Delta\lambda$	-	50	-	nm	$I_F = 1 \text{ A}$
Forward Voltage	V_F	-	1.9	2.5	V	$I_F = 1 \text{ A}$
Reverse Current	I_R	-	-	10	μA	$V_R = 5 \text{ V}$
Rise/Fall Time	T_r/T_f	-	30	-	ns	10%~90%
Viewing Angle (See FIG.6)	$2\theta_{1/2}$	-	90	-	deg.	

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25°C Ambient Temperature Unless Otherwise Noted)

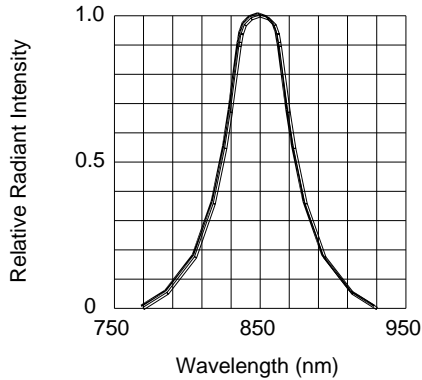


FIG.1 SPECTRAL DISTRIBUTION

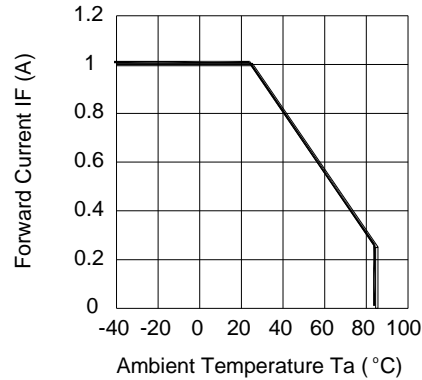


FIG.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

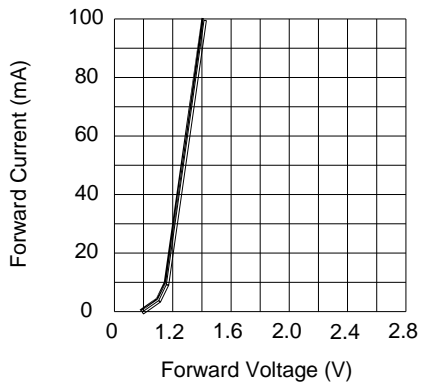


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

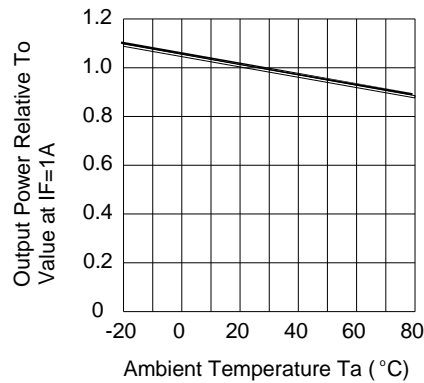


FIG.4 RELATIVE RADIANT INTENSITY VS. AMBIENT TEMPERATURE

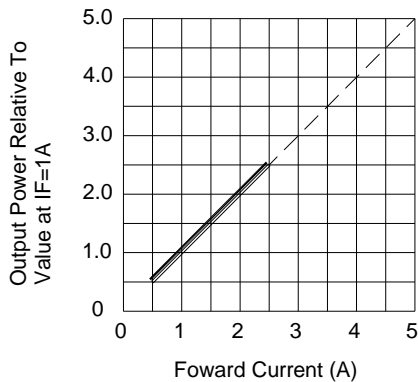


FIG.5 RELATIVE RADIANT INTENSITY VS. FORWARD CURRENT

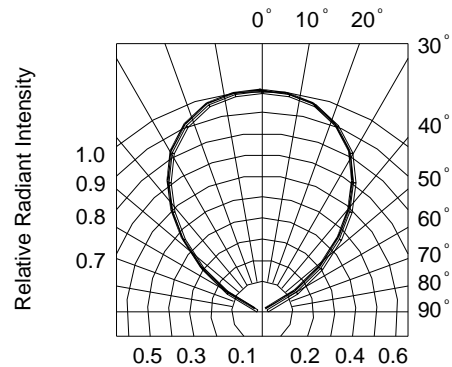
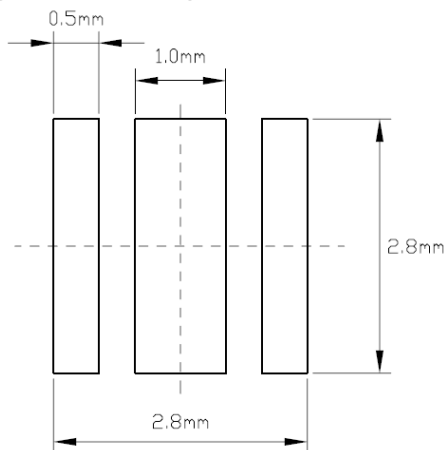
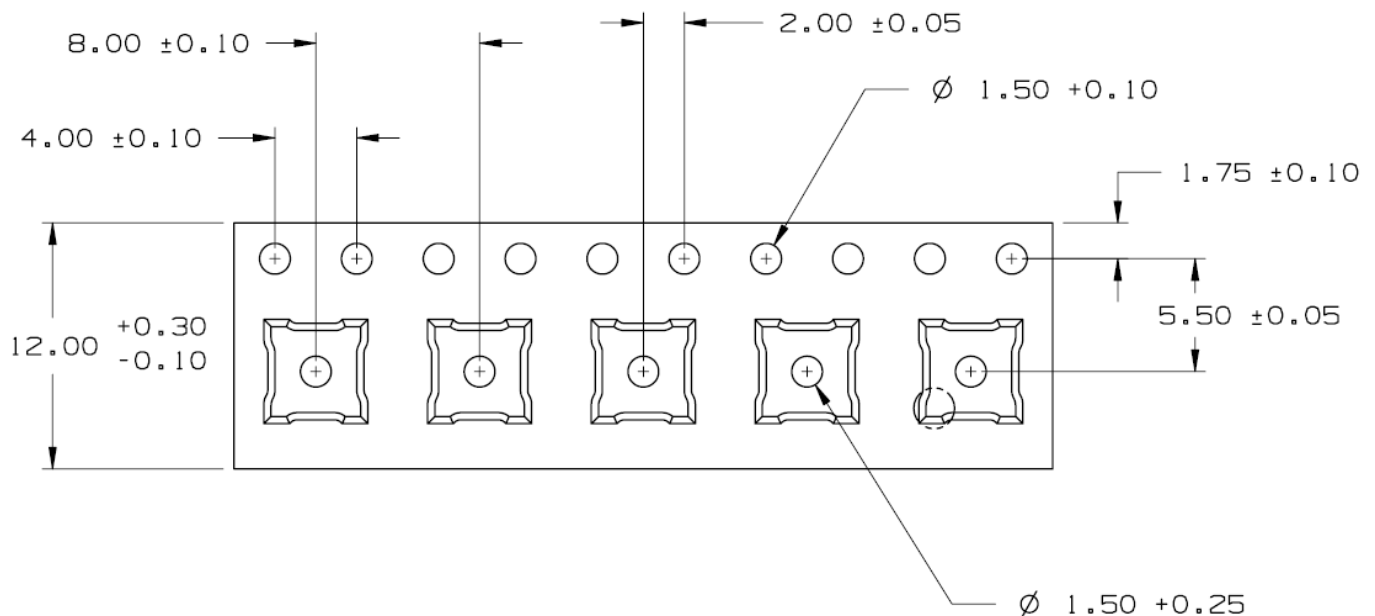


FIG.6 RADIATION DIAGRAM

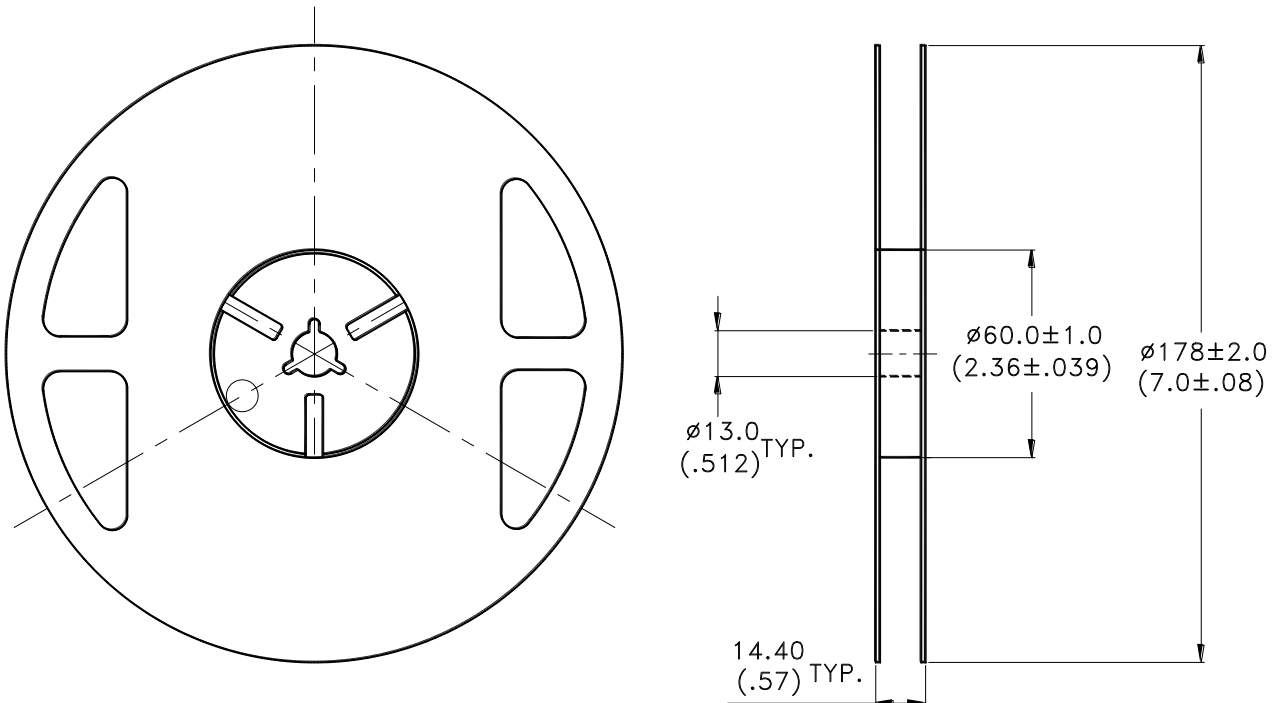
Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package.

If clean is necessary, immerse the LED in ethyl alcohol or in isopropyl alcohol at normal temperature for less one minute.

Suggest Soldering Pad Dimensions**Package Dimensions Of Tape And Reel****Notes:**

1. All dimensions are in millimeters (inches).

**Notes:**

1. All dimensions are in millimeters (inches).
2. Empty component pockets sealed with top cover tape.
3. 7 inch reel-600 pieces per reel.
4. The maximum number of consecutive missing lamps is two.
5. In accordance with ANSI/EIA 481-1-A-1994 specifications.

CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

The package is sealed:

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

The storage ambient for the LEDs should not exceed 30°C temperature or 60% relative humidity.

It is recommended that LEDs out of their original packaging are IR-reflowed within one week hrs.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant, or in a desiccators with nitrogen ambient.

LEDs stored out of their original packaging for more than one week hrs should be baked at about 60 deg C for at least 20 hours before solder assembly.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

4. Soldering

Recommended soldering conditions:

Reflow soldering		Soldering iron	
Pre-heat	150~200°C	Temperature	300°C Max.
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.
Peak temperature	260°C Max.		(one time only)
Soldering time	10 sec. Max.(Max. two times)		

Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

LITE-ON Runs both component-level verification using in-house **KYRAMX98** reflow chambers and board-level assembly.

The results of this testing are verified through post-reflow reliability testing.

Profiles used at LITE-ON are based on JEDEC standards to ensure that all packages can be successfully and reliably surface mounted.

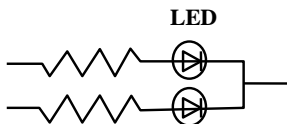
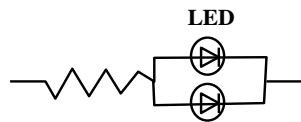
Figure on page3 shows a sample temperature profile compliant to JEDEC standards.

You can use this example as a generic target to set up your reflow process.

You should adhere to the JEDEC profile limits as well as specifications and recommendations from the solder paste manufacturer to avoid damaging the device and create a reliable solder joint.

5. Drive Method

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A**Circuit model B**

(A) Recommended circuit.

(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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